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FOR IMMEDIATE RELEASE

Press Release

YINCAE to Showcase Innovative Products at Apex 2026

(Albany, NY) — 1/20/2026 — YINCAE Advanced Materials Co., Ltd. (YINCAE), a leading developer and manufacturer of high-performance semiconductor and electronics assembly materials, announced today it will exhibit at Apex 2026, held March 16–19, 2026 at the Anaheim Convention Center .

YINCAE invites attendees to visit our **Booth #4130** to explore its latest electronics assembly and packaging material solutions engineered to support higher reliability, improved process yield, and robust thermal/mechanical performance for next-generation electronic systems.

Apex brings together decision makers and technical professionals across electronics manufacturing, SMT/PCBA assembly, advanced packaging, automotive and industrial electronics, and other high-reliability applications. At Booth #4130, YINCAE will feature materials designed to address key production and performance challenges, including void reduction, thermal cycling reliability, warpage control, and high-throughput manufacturing compatibility.

YINCAE will showcase:

- Underfill Materials (Capillary & Molded Underfill / Reinforcement) designed to enhance drop performance, thermal cycling reliability, and mechanical reinforcement for advanced components and fine-pitch assemblies.
- Die Attach & Structural Adhesives engineered for high adhesion strength, temperature stability, and long-term reliability in electronics and semiconductor assembly.
- Thermal Interface Materials (TIMs) formulated to improve heat dissipation and maintain stable performance in high-power and thermally demanding designs.
- High-Reliability Assembly Materials for Advanced Electronics supporting applications in HPC/AI, automotive electronics, communications, industrial controls, and high-density packaging.

Please stop by Booth #4130 to connect with YINCAE technical experts and learn more about YINCAE’s advanced material solutions, including capillary underfills, molded underfills, die attach/structural adhesives, and thermal interface materials (TIMs) engineered for fine-pitch compatibility, no voiding, warpage control, and enhanced thermal cycling and mechanical reliability in high-density, high-power electronic systems. For more information, please contact info@yincae.com or visit www.yincae.com.

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Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of high-performance coatings, adhesives and electronic materials used in the microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

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